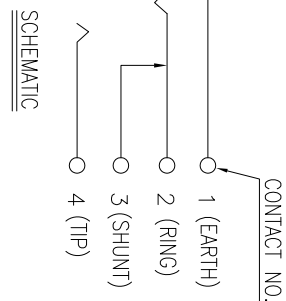
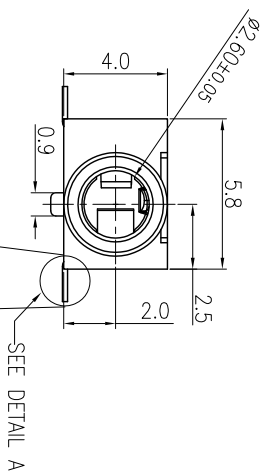
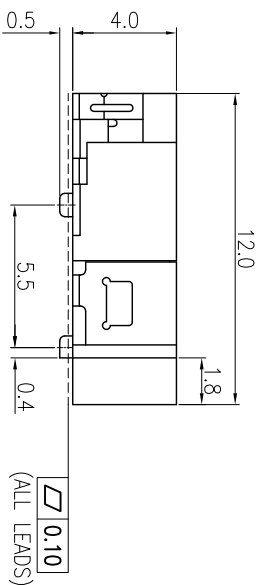
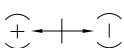


RECOMMENDED PC BOARD LAYOUT
(TOL. ±0.05)(TOP VIEW)



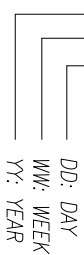
DETAIL A
SCALE 10:1



REV.	ECN NO.	OR DESCRIPTION	REVISED	DATE
C	ADD	DATE CODE	HAI HUA	2007.08.07
D	2.ECN NO.	C070303-3/4. 1.變更EARTH結構	羅華華	2008.05.02.
E	ECN:C120311	MODIFY D/C	DAOWEN	2012.11.26

- NOTES:
- SPECIFICATIONS:
 - INSULATION RESISTANCE BETWEEN ANY ADJACENT OPEN CIRCUIT TERMINAL SHALL NOT BE LESS THAN 100MΩ MEASURED BY 500V DC MEGGER.
 - CONTACT RESISTANCE:30mΩ MAX.
 - INSULATION VOLTAGE WITHSTAND:500V AC FOR ONE MINUTE.
 - TEST IS TO BE MADE AT 5~35° IN TEMPERATURE AND 45~85% IN HUMIDITY.
 - INSERTION FORCE:0.3~3kg.
 - EXTRACTION FORCE:0.3~3kg.
 - SOLDER HEAT RESISTANCE:REFLOW SOLDERING 260° FOR 10SECS.
 - TO CONFORM TO THE SINGATRON HSF SPEC.
 - GREEN PRODUCT IDENTIFICATION MARK ON JACK.
 - GREEN PRODUCT IDENTIFICATION LABEL ON PACKAGING: **G.P. PASS**
 - FOR REFLOW SOLDERING LEED-FREE PROCESS.
 - PRINTED DATE CODE" YMD " ON TOP OF CONNECTOR.

DATE CODE: Y W D



E	SHUNT	1	C2680R-H.0.25T	Au 3U"Min. Ni: 50U"Min.
D	TIP	1	C5210R-EH.0.25T	Ag 20U"Min. Ni: 50U"Min.
C	RING	1	C17460-HI.0.2T	Au 3U"Min. Ni: 50U"Min.
B	EARTH	1	C5210R-EH.0.25T	Ag 20U"Min. Ni: 50U"Min.
A	BODY	1	PA9T W/ 30%	BLACK COLOR
			GFJL94V-0	
NO	DESCRIPTION	QTY	MATERIAL	PLATING & COLOR
UNLESS OTHERWISE SPECIFIED TOLERANCES				
Singatron Enterprise Co., Ltd. 信登企業股份有限公司				
TITLE: 2.5ØPHONE JACK				
DWN	DATE: 2012.11.27	PART NO.	2SJ-ST02-002	
CHKD	DATE: 2012.11.27	SCALE	5:1	UNIT: mm
APVD	DATE: 2012.11.23	SIZE:	A3	SHEET: 10F1 REV: E
CUSTOMER COPY				